Typical advantages of using low voltage motors for the pump are:

-- Low voltage motor driver ICs offer high protection feature integrations compared to high voltage IPMs. They have completely integrated MOSFET drivers, Low RDSON Power MOSFETs, Over current protection using VDS Sensing, Over temperature protection, Auto restart etc., while offering lower switching losses.

-- Manufacturing of "low voltage-low power motors" is easier than "high voltage-low power motors" and there is small cost saving.

-- As the motors are 24V rated, same motors can be used for 110V / 220V line voltage based products and wide line input conditions. The same design can also be compatible with solar operated Dish washers.
You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
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<tr>
<td>001</td>
<td>ChangeMe!</td>
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<tr>
<td>002</td>
<td>ChangeMe!</td>
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These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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